

SOT102-2

plastic dual in-line package; 18 leads (300 mil); slim corner leads

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DIP18
Package type industry code	DIP18
Package style descriptive code	DIP (dual in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-011
Mounting method type	T (through-hole mount)
Issue date	13-2-2003

Table 1. Package summary

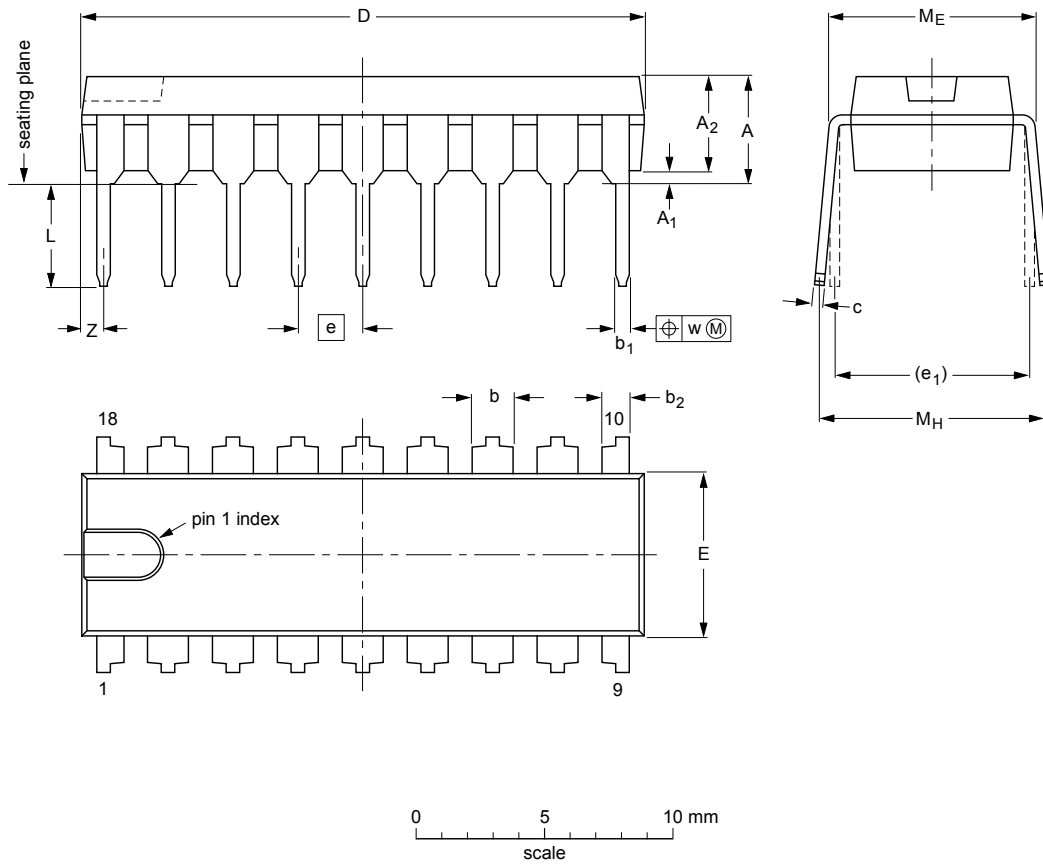
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	21.4	-	21.6	21.8	mm
E	package width	6.2	-	6.34	6.48	mm
A	seated height	[tbd]	-	[tbd]	4.7	mm
A ₂	package height	[tbd]	-	[tbd]	3.7	mm
e	nominal pitch	-	-	2.54	-	mm
n ₂	actual quantity of termination	-	-	18	-	



2. Package outline

DIP18: plastic dual in-line package; 18 leads (300 mil); slim corner leads

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DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	b ₂	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.7	0.51	3.7	1.40 1.14	0.53 0.38	1.05 0.75	0.32 0.23	21.8 21.4	6.48 6.20	2.54	7.62	3.9 3.4	8.25 7.80	9.5 8.3	0.254	0.85
inches	0.19	0.02	0.15	0.055 0.045	0.021 0.015	0.041 0.030	0.013 0.009	0.86 0.84	0.26 0.24	0.1	0.3	0.15 0.13	0.32 0.31	0.37 0.33	0.01	0.033

Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT102-2		MS-011			99-12-27 03-02-13

Fig. 1. Package outline DIP18 (SOT102-2)

3. Legal information

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